

METHOD AND SYSTEM FOR PACKAGING BALL GRID ARRAYS

ABSTRACT OF THE DISCLOSURE

5 According to one embodiment of the invention, a method of packaging ball grid arrays includes providing a substrate having a plurality of holes formed therein. Each hole is associated with a respective one of a plurality of contact pads formed on a first surface of the substrate. The method further includes disposing a plurality of balls within respective ones of the plurality of holes such that at least a portion of each ball projects outwardly from the first surface, and applying a force to each of the balls from above the first surface to couple the balls to the substrate.